

ABSTRACT

A semiconductor apparatus is disclosed.

The semiconductor apparatus comprises a substrate

5 with a pad, an internal circuitry region, and a

protection resistance formed on the substrate. The

pad is connected to a first electrode of the

protection resistance by wiring, the internal

circuitry region is connected to a second electrode

10 of the protection resistance by wiring, and the

protection resistance protects the internal

circuitry region from electrostatic discharging.

The semiconductor apparatus is characterized in

that the pad is placed between the protection

15 resistance and the internal circuitry region.